

N and P-Channel Enhancement Mode Power MOSFET

Description

The K4614 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

● N-Channel

$$V_{DS} = 40V, I_D = 8.0A$$

$$R_{DS(ON)} < 22m\Omega @ V_{GS}=10V$$

$$R_{DS(ON)} < 31m\Omega @ V_{GS}=4.5V$$

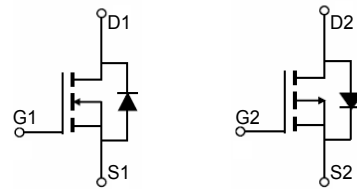
● P-Channel

$$V_{DS} = -40V, I_D = -7.0A$$

$$R_{DS(ON)} < 35m\Omega @ V_{GS}=-10V$$

$$R_{DS(ON)} < 48m\Omega @ V_{GS}=-4.5V$$

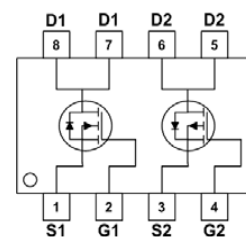
- High power and current handling capability
- Lead free product is acquired
- Surface mount package



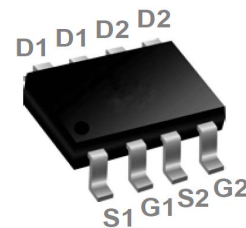
N-channel

P-channel

Schematic diagram



Marking and pin assignment



SOP-8 top view

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V_{DS}	40	-40	V
Gate-Source Voltage		V_{GS}	± 20	± 20	V
Continuous Drain Current	$T_A=25^\circ\text{C}$	I_D	8.0	-7.0	A
Pulsed Drain Current ^(Note 1)		I_{DM}	40	-30	A
Maximum Power Dissipation	$T_A=25^\circ\text{C}$	P_D	2.0	2.0	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 To 150	-55 To 150	$^\circ\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note2)	$R_{\theta JA}$	N-Ch	62.5	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient ^(Note2)	$R_{\theta JA}$	P-Ch	62.5	$^\circ\text{C/W}$

N-CH Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA

On Characteristics (Note 3)

Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A	-	16	22	mΩ
		V _{GS} =4.5V, I _D =6A	-	18	31	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =8A	15	-	-	S

Dynamic Characteristics (Note4)

Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, F=1.0MHz	-	1137	-	PF
Output Capacitance	C _{oss}		-	84.5	-	PF
Reverse Transfer Capacitance	C _{rss}		-	72.5	-	PF

Switching Characteristics (Note 4)

Turn-on Delay Time	t _{d(on)}	V _{DD} =20V, I _D =8.0A V _{GS} =10V, R _G =3.0Ω	-	6.0	-	nS
Turn-on Rise Time	t _r		-	20.3	-	nS
Turn-Off Delay Time	t _{d(off)}		-	26.2	-	nS
Turn-Off Fall Time	t _f		-	12.8	-	nS
Total Gate Charge	Q _g	V _{DS} =20V, I _D =8A, V _{GS} =10V	-	25.8	-	nC
Gate-Source Charge	Q _{gs}		-	3.65	-	nC
Gate-Drain Charge	Q _{gd}		-	4.41	-	nC

Drain-Source Diode Characteristics

Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =8A	-	0.75	1.0	V
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Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

N- Channel Typical Electrical and Thermal Characteristics (Curves)

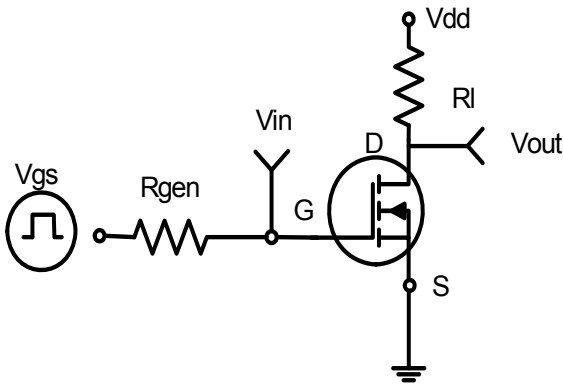


Figure 1: Switching Test Circuit

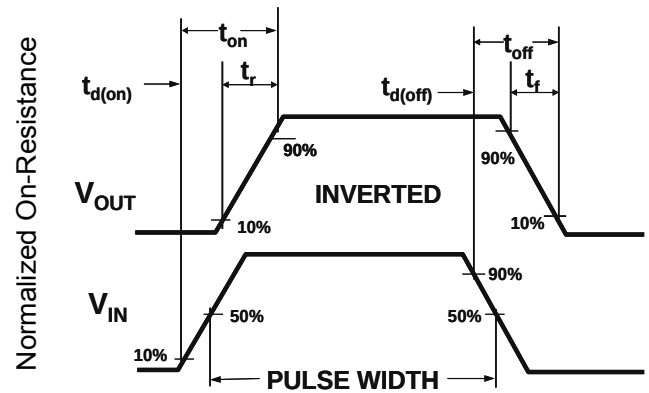


Figure 2: Switching Waveforms

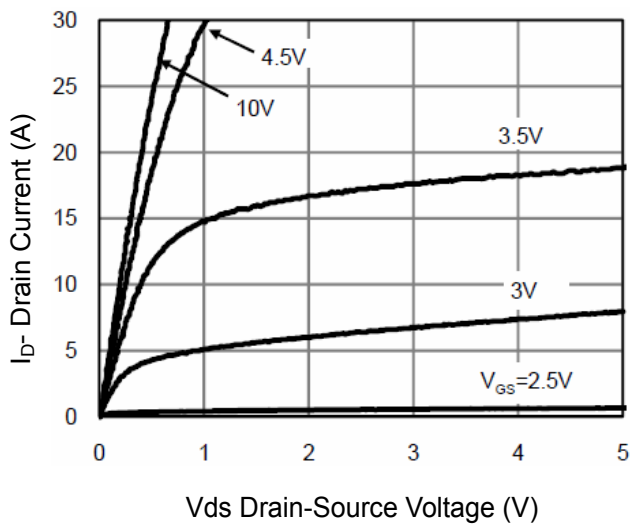


Figure 3 Output Characteristics

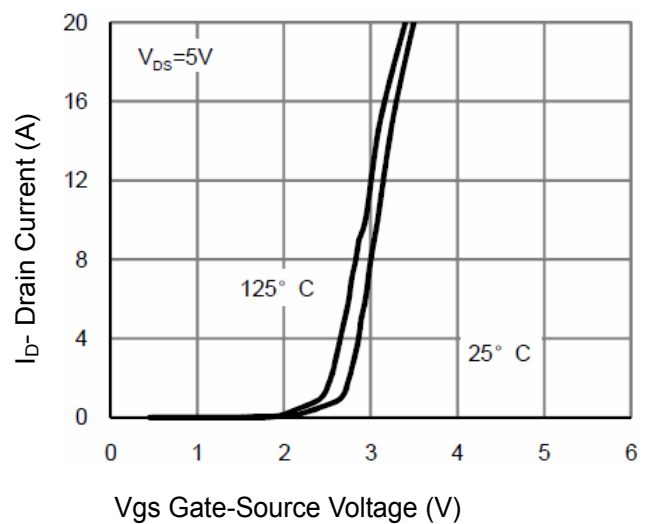


Figure 4 Transfer Characteristics

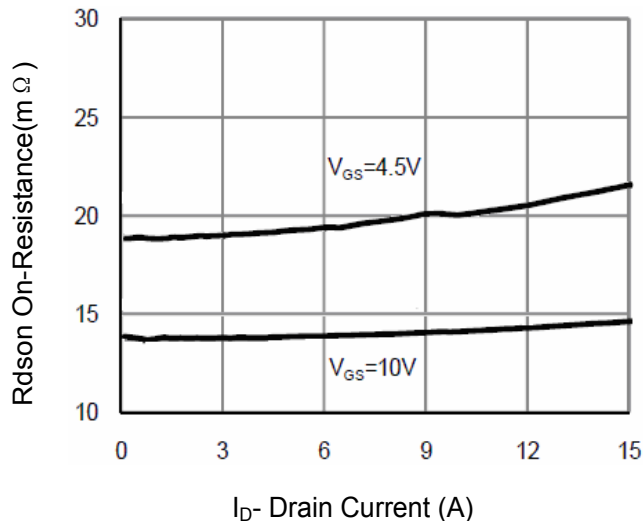


Figure 5 Drain-Source On-Resistance

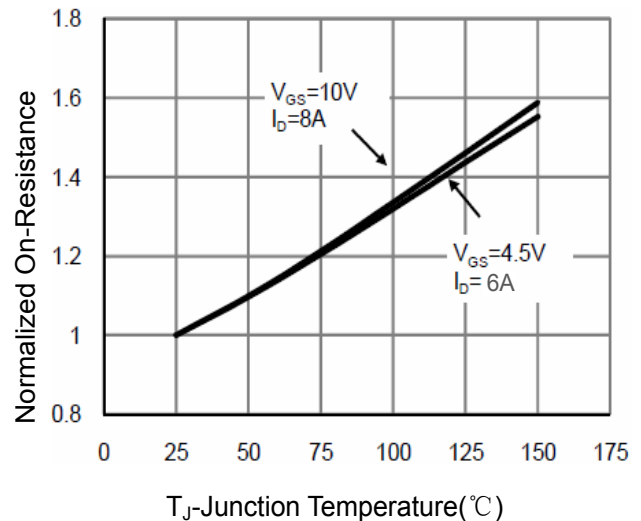
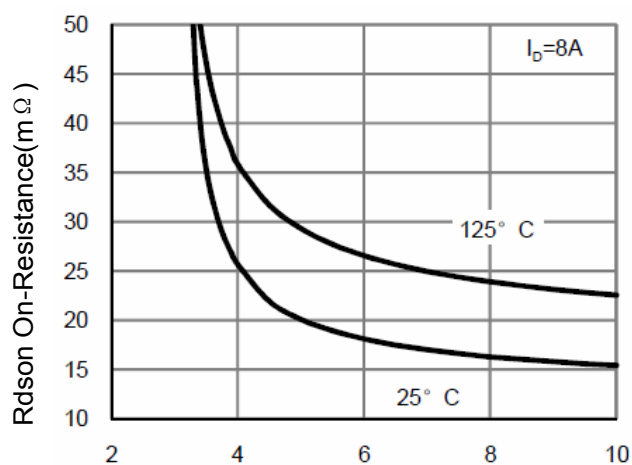
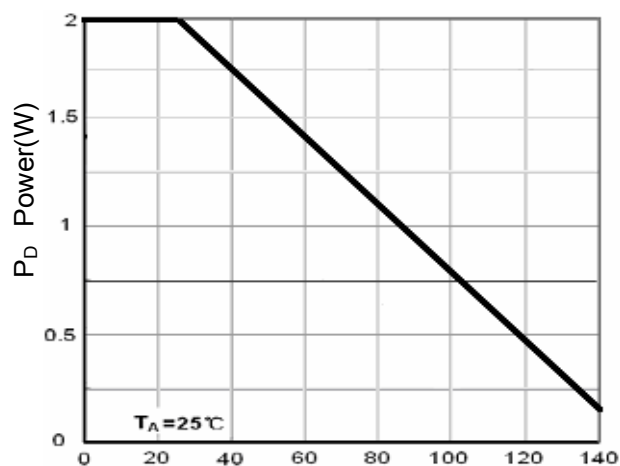


Figure 6 Drain-Source On-Resistance



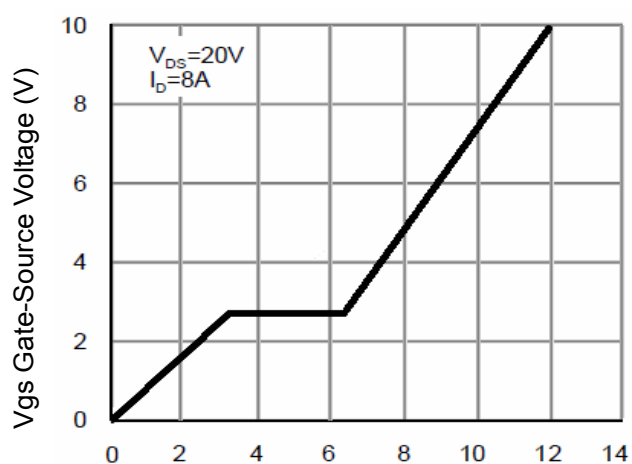
Vgs Gate-Source Voltage (V)

Figure 7 Rdson vs Vgs



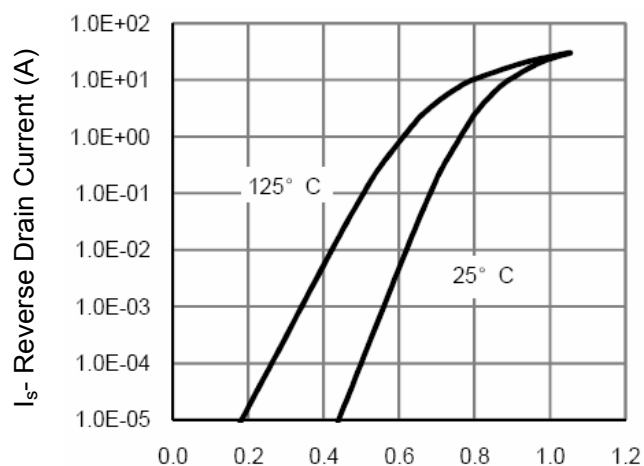
Tj Junction Temperature (°C)

Figure 8 Power Dissipation



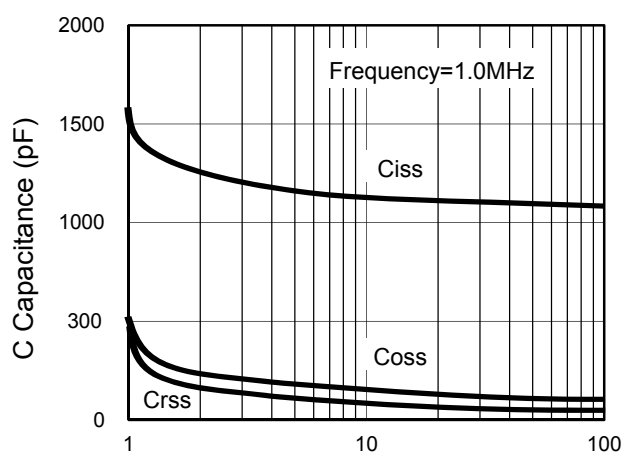
Qg Gate Charge (nC)

Figure 9 Gate Charge



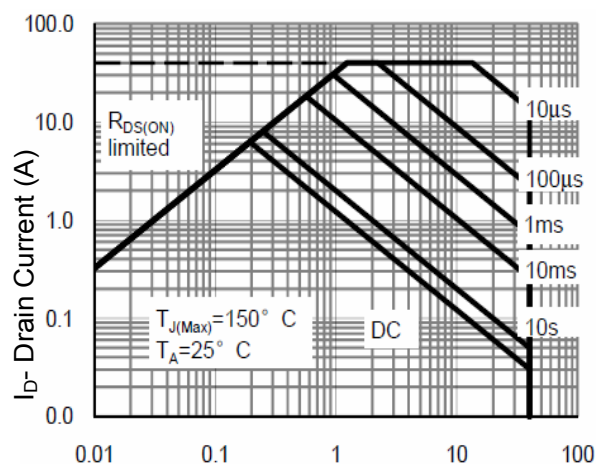
Vds Drain-Source Voltage (V)

Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 11 Capacitance vs Vds



Vds Drain-Source Voltage (V)

Figure 12 Safe Operation Area

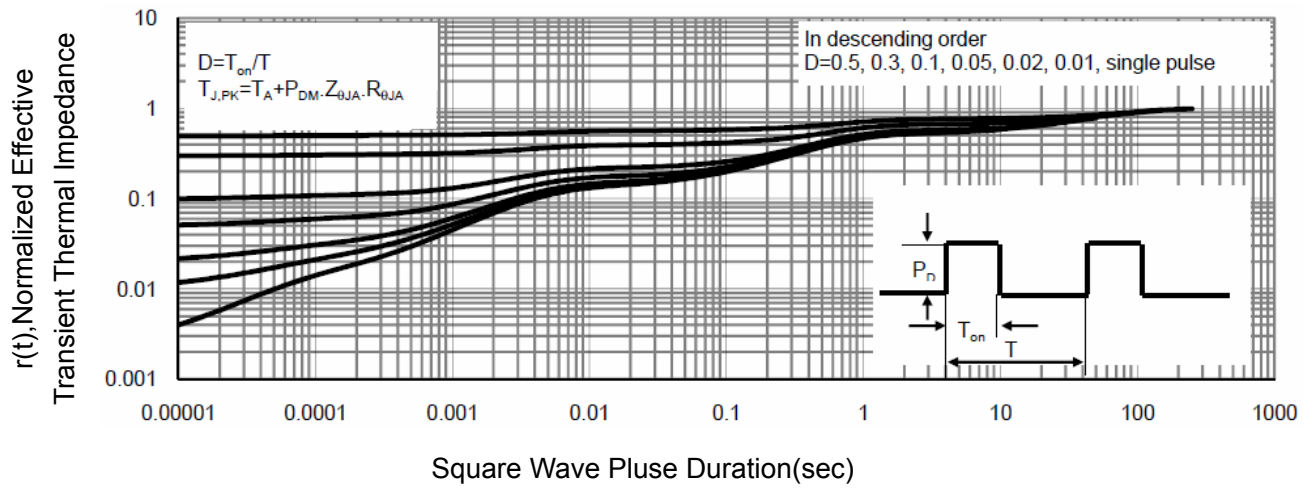


Figure 13 Normalized Maximum Transient Thermal Impedance

P-CH Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V, V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA

On Characteristics ^(Note 3)

Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.1	-1.8	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-7.0A	-	30	35	mΩ
		V _{GS} =-4.5V, I _D =-4.0A	-	43	48	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-7.0A	15	-	-	S

Dynamic Characteristics ^(Note 4)

Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V, F=1.0MHz	-	1277	-	PF
Output Capacitance	C _{oss}		-	105.7	-	PF
Reverse Transfer Capacitance	C _{rss}		-	100.7	-	PF

Switching Characteristics ^(Note 4)

Turn-on Delay Time	t _{d(on)}	V _{DD} =-20V, I _D =-7.0A V _{GS} =-10V, R _G =10Ω	-	7.0	-	nS
Turn-on Rise Time	t _r		-	18.5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	71.6	-	nS
Turn-Off Fall Time	t _f		-	27.5	-	nS
Total Gate Charge	Q _g	V _{DS} =-20V, I _D =-7.0A V _{GS} =-10V	-	28.2	-	nC
Gate-Source Charge	Q _{gs}		-	4.1	-	nC
Gate-Drain Charge	Q _{gd}		-	5.3	-	nC

Drain-Source Diode Characteristics

Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V, I _S =-7.0A	-	0.75	-1.0	V
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Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

P- Channel Typical Electrical and Thermal Characteristics (Curves)

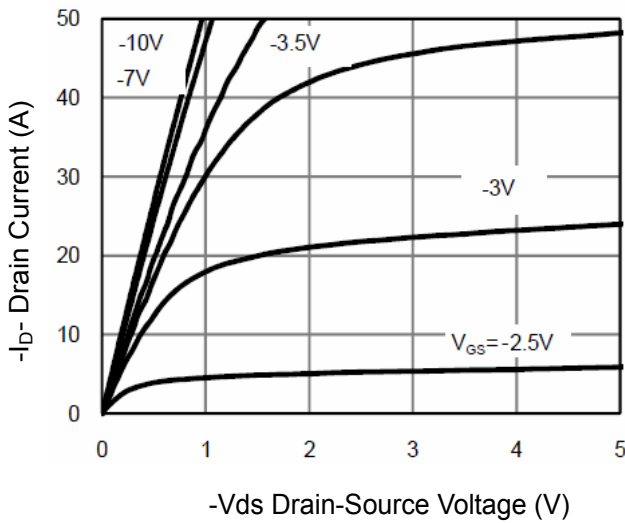


Figure 1 Output Characteristics

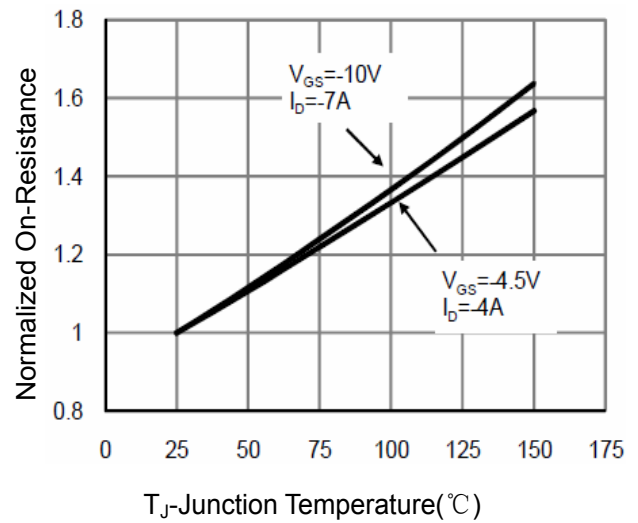


Figure 4 Rdson-Junction Temperature

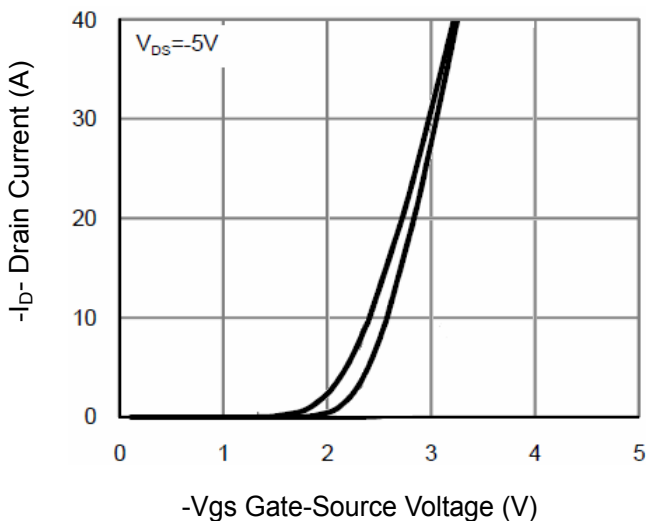


Figure 2 Transfer Characteristics

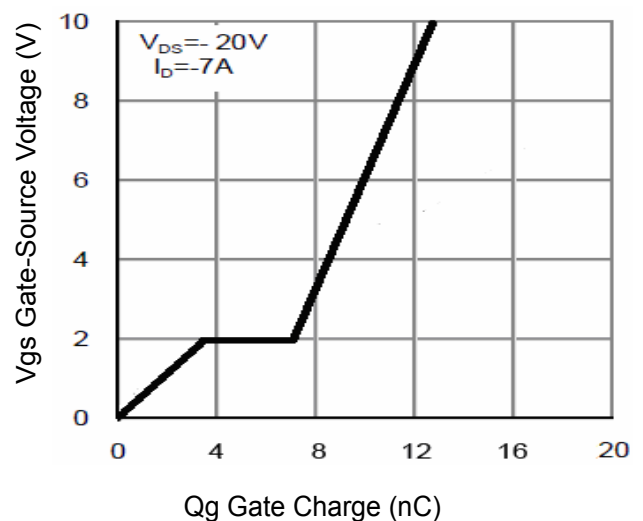


Figure 5 Gate Charge

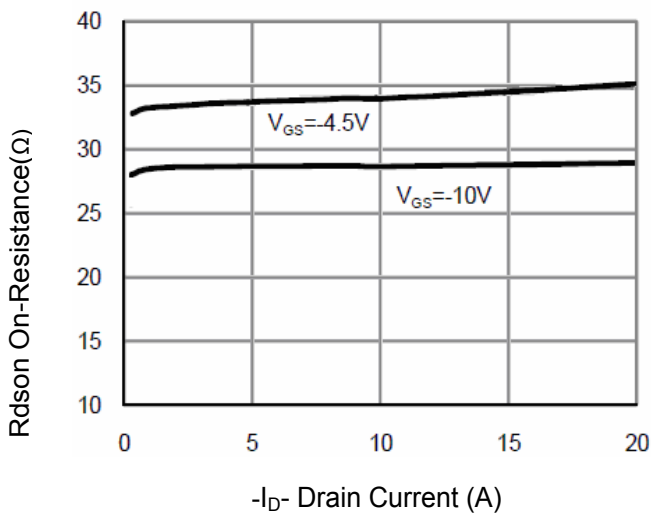


Figure 3 Rdson- Drain Current

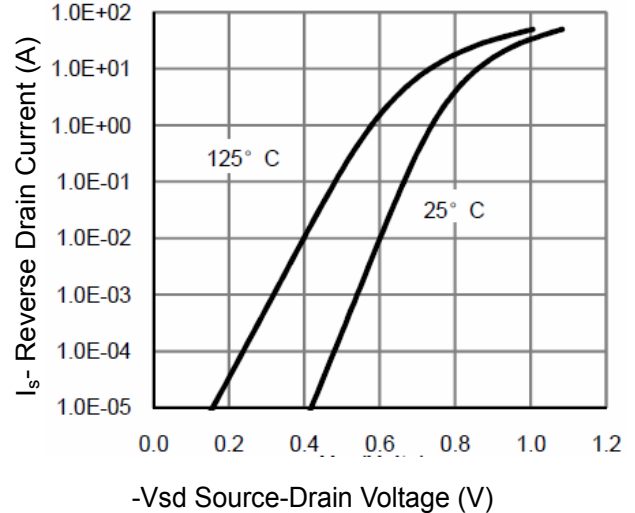


Figure 6 Source- Drain Diode Forward

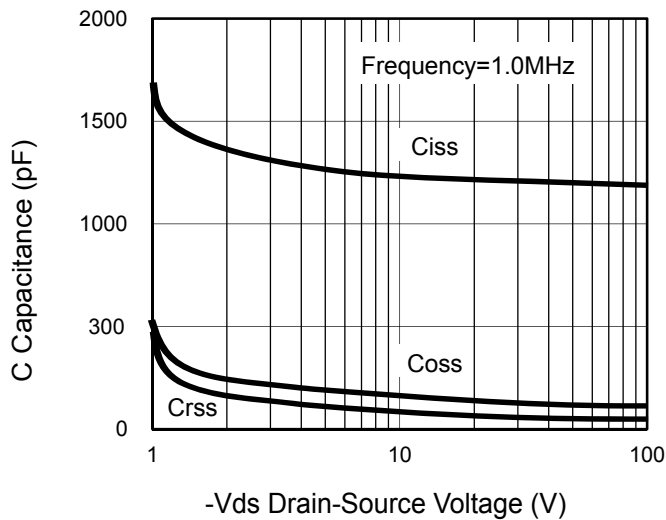


Figure 7 Capacitance vs Vds

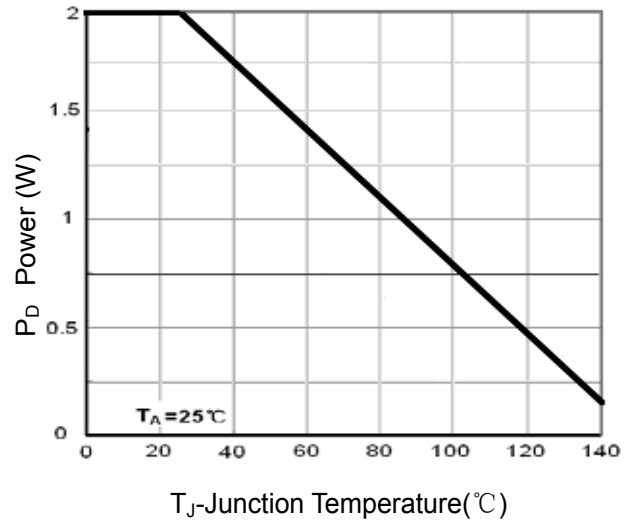


Figure 9 Power Dissipation

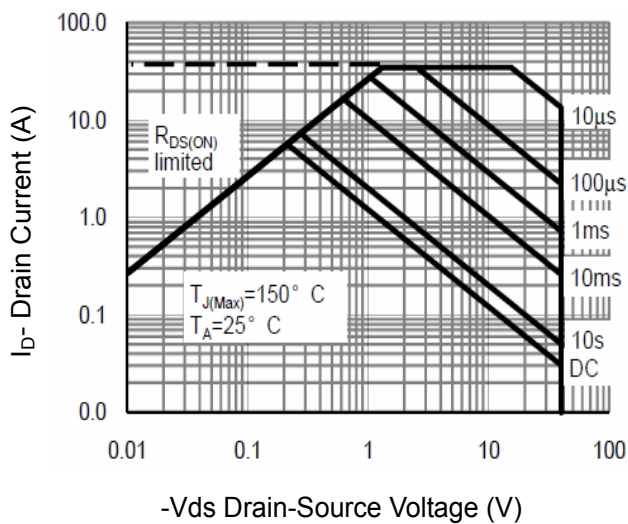


Figure 8 Safe Operation Area

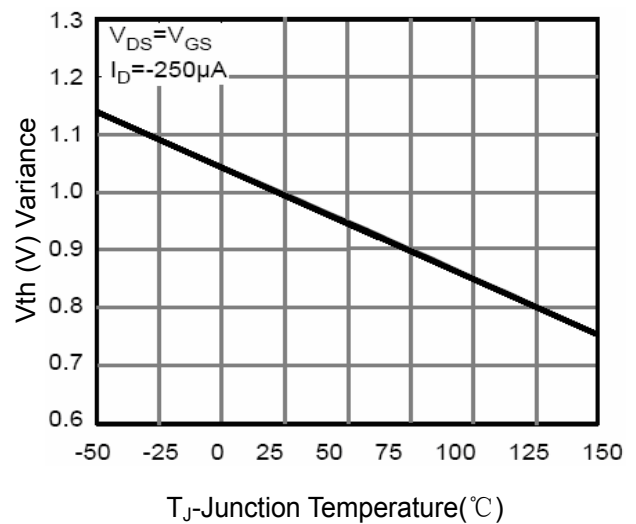


Figure 10 $V_{GS(th)}$ vs Junction Temperature

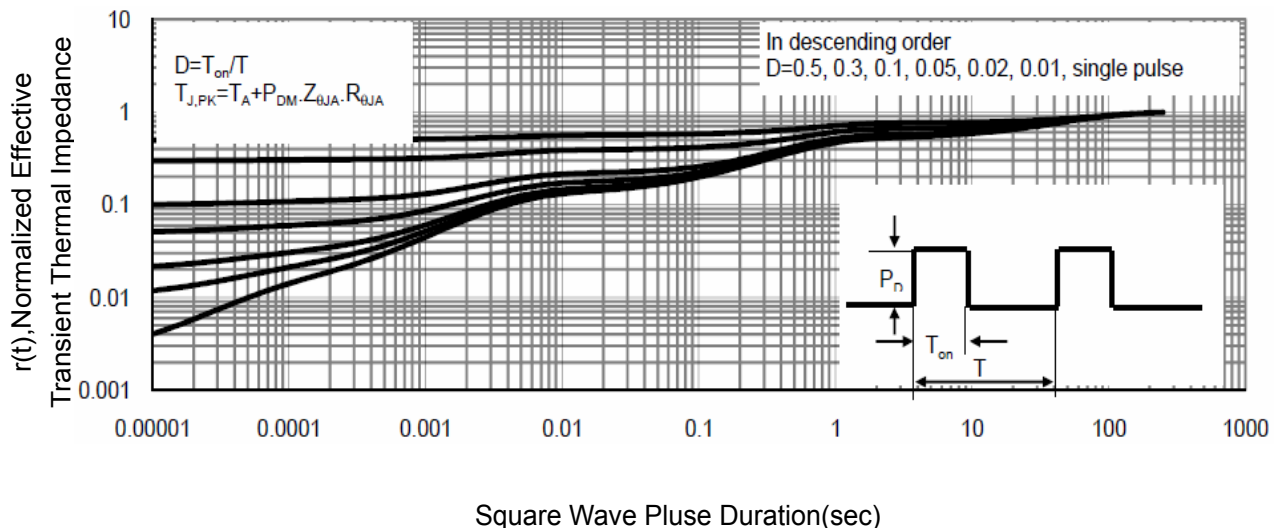
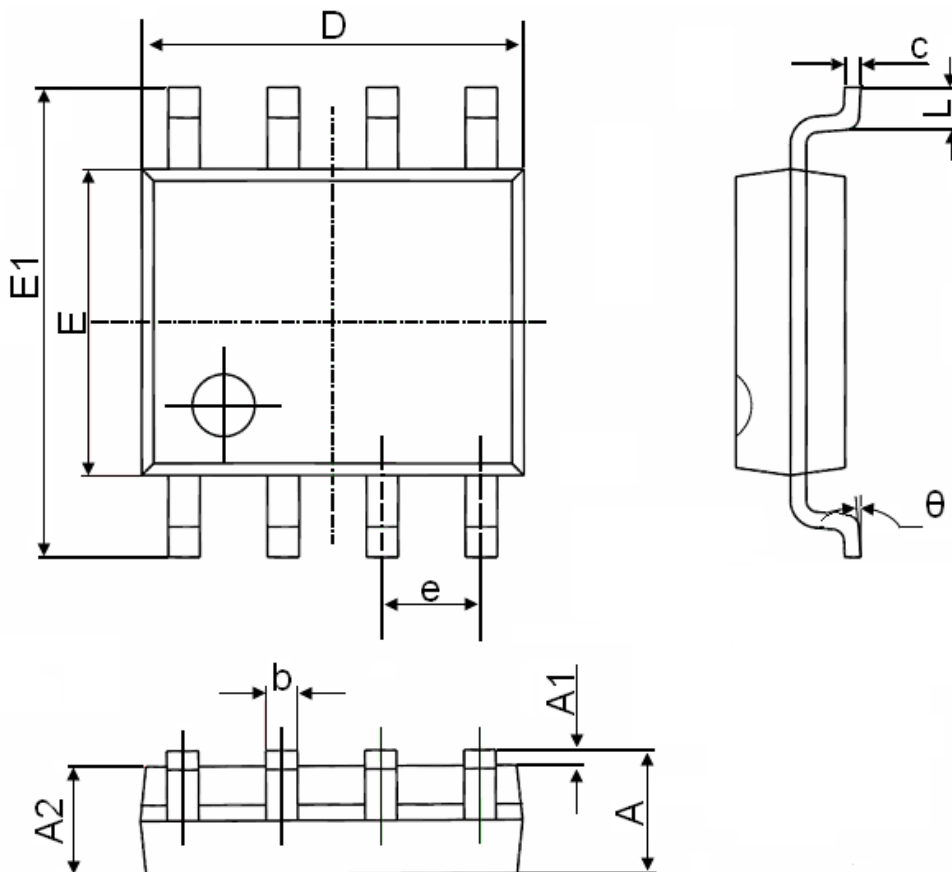


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°